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RF7234

3V TD-SCDMA/W-CDMA LINEAR PA MODULE BAND 1 AND 1880MHz TO 2025MHz

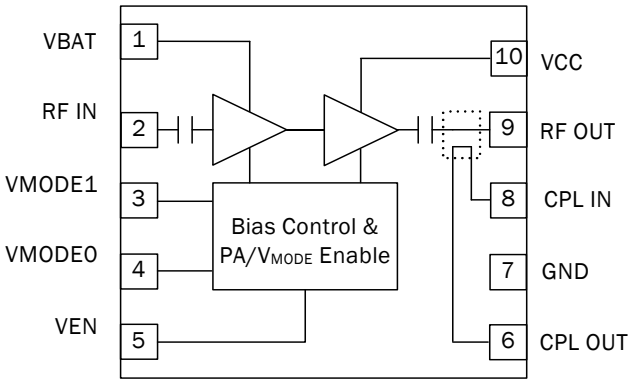
Package Style: Module, 10-Pin, 3mmx3mmx1.0mm

Features

- TD-SCDMA and HSDPA Compliant
- Low Voltage Positive Bias Supply (3.4V to 4.2V)
- +28dBm Linear Output Power W-CDMA (+26.5dBm HSDPA)
- +27.5dBm Output Power TD-SCDMA
- High Efficiency Operation 35% at P_{OUT}=+27.5dBm (TD-SCDMA)
- 20% at P_{OUT}=+19.0dBm (Without DC/DC Converter)
- Low Quiescent Current in Low Power Mode: 17mA
- Internal Voltage Regulator Eliminates the Need for External Reference Voltage (V_{REF})
- 3-Mode Power States with Digital Control Interface
- Supports DC/DC Converter Operation
- Integrated Power Coupler
- Integrated Blocking and Collector Decoupling Capacitors

Applications

- TD-SCDMA/HSDPA/W-CDMA Wireless Handsets and Data Cards
- Dual-Mode UMTS Wireless Handsets



Functional Block Diagram

Product Description

The RF7234 is a high-power, high-efficiency, linear power amplifier designed for use as the final RF amplifier in 3V, 50Ω TD-SCDMA mobile cellular equipment and spread-spectrum systems. This PA is developed for TD-SCDMA 1880MHz to 1920MHz and 2010MHz to 2025MHz frequency band, plus W-CDMA Band 1. The RF7234 has two digital control pins to select one of three power modes to optimize performance and current drain at lower power levels. The part also has an integrated directional coupler which eliminates the need for an external discrete coupler at the output. The RF7234 is fully TD-SCDMA/W-CDMA/HSDPA-compliant and is assembled in a 10-pin, 3mmx3mm module.

Ordering Information

RF7234	3V TD-SCDMA/W-CDMA Linear PA Module Band 1 and 1880MHz to 2025MHz
RF7234PCBA-410	Fully Assembled Evaluation Board

Optimum Technology Matching® Applied

☐ GaAs HBT	☐ SiGe BiCMOS	☐ GaAs pHEMT	☐ GaN HEMT
☐ GaAs MESFET	☐ Si BiCMOS	☐ Si CMOS	☐ RF MEMS
☑ InGaP HBT	☐ SiGe HBT	☐ Si BJT	☐ LDMOS

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Absolute Maximum Ratings

Parameter	Rating	Unit
Supply Voltage in Standby Mode	6.0	V
Supply Voltage in Idle Mode	6.0	V
Supply Voltage in Operating Mode, 50Ω Load	6.0	V
Supply Voltage, V_{BAT}	6.0	V
Control Voltage, VMODE0, VMODE1	3.5	V
Control Voltage, V_{EN}	3.5	V
RF - Input Power	+6	dBm
RF - Output Power	+30	dBm
Output Load VSWR (Ruggedness)	10:1	
Operating Ambient Temperature	-30 to +110	°C
Storage Temperature	-55 to +150	°C

Caution! ESD sensitive device.

Exceeding any one or a combination of the Absolute Maximum Rating conditions may cause permanent damage to the device. Extended application of Absolute Maximum Rating conditions to the device may reduce device reliability. Specified typical performance or functional operation of the device under Absolute Maximum Rating conditions is not implied.

RoHS status based on EUDirective2002/95/EC (at time of this document revision).

Parameter	Specification			Unit	Condition
	Min.	Typ.	Max.		
Recommended Operating Conditions					T=25°C, V_{CC}=V_{BATT}=3.4V, V_{EN}=1.8V, 50Ω, TD-SCDMA or W-CDMA-GTC1 Modulation, unless otherwise specified.
Operating Frequency Range	1880		1920	MHz	TD-SCDMA
	1920		1980	MHz	W-CDMA
	2010		2025	Hz	TD-SCDMA
V_{BAT}	+3.2[1]	+3.4	+4.2	V	
V_{CC}	+3.2[1]	+3.4	+4.2	V	
V_{EN}	0		0.5	V	PA disabled.
	1.4	1.8	3.0	V	PA enabled.
V_{MODE0}, V_{MODE1}	0		0.5	V	Logic “low”.
	1.4	1.8	3.0	V	Logic “high”.
P_{OUT}					
Maximum Linear Output (HPM)	28[2]			dBm	High Power Mode W-CDMA (HPM)
Maximum Linear Output (HPM)	27.5[2]			dBm	High Power Mode (HPM) TD-SCDMA
Maximum Linear Output (MPM)	19.0[2]			dBm	Medium Power Mode (MPM)
Maximum Linear Output (LPM)	8.0[2]			dBm	Low Power Mode (LPM)
Ambient Temperature	-25	+25	+85	°C	

Notes:

[1]Minimum V_{CC} for max P_{OUT} is indicated. V_{CC} down to 0.5V may be used for backed-off power when using DC/DC converter to conserve battery current.

[2]For operation at below V_{CC}=3.4V, derate P_{OUT} by 1.0dB.

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Parameter	Specification			Unit	Condition
	Min.	Typ.	Max.		
Electrical Specifications - W-CDMA					T=+25°C, V_{CC}=V_{BAT}=+3.4V, V_{EN}=+1.8V, 50Ω, W-CDMA modulation unless otherwise specified.
Gain	25	26.5		dB	HPM, P_{OUT}=28.0dBm, W-CDMA
	15	17.5		dB	MPM, P_{OUT}≤19.0dBm
	11[1]	14.5		dB	LPM, P_{OUT}≤8.0dBm
Gain Linearity		±0.2		dB	HPM, 19.0dBm≤P_{OUT}≤28.0dBm
ACLR - 5MHz Offset		-40		dBc	HPM, P_{OUT}=28.0dBm
		-46		dBc	MPM, P_{OUT}=19.0dBm
		-44		dBc	LPM, P_{OUT}=8.0dBm
ACLR - 10MHz Offset		-55		dBc	HPM, P_{OUT}=28.0dBm
		-60		dBc	MPM, P_{OUT}=19.0dBm
		-64		dBc	LPM, P_{OUT}=8.0dBm
PAE Without DC/DC Converter		40		%	HPM, P_{OUT}=28.0dBm
		20		%	MPM, P_{OUT}=19.0dBm
Current Drain		80		mA	MPM, P_{OUT}=16.0dBm
		37		mA	LPM, P_{OUT}=8.0dBm
		20		mA	LPM, P_{OUT}=0.0dBm
Quiescent Current		85		mA	HPM, DC only
		20		mA	MPM, DC only
		17		mA	LPM, DC only
Enable Current		0.3	1.0	mA	Source or sink current. V_{EN}=1.8V.
Mode Current (I_{MODE0}, I_{MODE1})		0.3	1.0	mA	Source or sink current. V_{MODE0}, V_{MODE1}=1.8V.
Leakage Current		1.0	10.0	µA	DC only. V_{CC}=V_{BAT}=3.7V, V_{EN}=V_{MODE0}=V_{MODE1}=0.5V.
Input Impedance		2.0:1		VSWR	No ext. matching, P_{OUT}≤28dBm, all modes.
Harmonic, 2FO		-28		dBm	P_{OUT}≤28.0dBm
Harmonic, 3FO		-35		dBm	P_{OUT}≤28.0dBm
Spurious Output Level			-70	dBc	All spurious, P_{OUT}≤28dBm, all conditions, load VSWR≤6:1, all phase angles.
Insertion Phase Shift	-30		+30	°	Phase shift at 19dBm when switching from HPM to MPM and MPM to LPM at 8dBm.
DC Enable Time			10	µS	DC only. Time from V_{EN}=high to stable idle current (90% of steady state value).
RF Rise/Fall Time			6	µS	P_{OUT}≤28.0dBm, all modes. 90% of target, DC settled prior to RF.
Coupling Factor		-19.5		dB	P_{OUT}≤28.0dBm, all modes.
Coupling Accuracy - Temp/Voltage		±0.5		dB	P_{OUT}≤28.0dBm, all modes. -30°C≤T≤85°C, 3.0V≤V_{CC} & V_{BAT}≤4.2V, referenced to 25°C, 3.4V conditions.
Coupling Accuracy - VSWR		±0.5		dB	P_{OUT}≤28dBm, all modes, load VSWR=2:1, ±0.5dB accuracy corresponds to 15dB directivity.

Note: [1]Excludes DC/DC converter operation. Gain may be lower when using DC/DC converter to conserve battery current.
Note: [2]Unless otherwise marked , each spec is equivalent for W-CDMA or TD-SCDMA operation.

Parameter	Specification			Unit	Condition
	Min.	Typ.	Max.		
Electrical Specifications - TD-SCDMA					T=+25°C, V_{CC}=V_{BAT}=+3.4V, V_{EN}=+1.8V, 50Ω, TD-SCDMA modulation unless otherwise specified.
Gain		26.5		dB	HPM, P_{OUT}=27.5dBm
	15	17.5		dB	MPM, P_{OUT}≤19.0dBm
	11[1]	14.5		dB	LPM, P_{OUT}≤8.0dBm
Gain Linearity		±0.2		dB	HPM, 19.0dBm≤P_{OUT}≤27.5dBm
ACLR - 1.6MHz Offset		-40		dBc	HPM, P_{OUT}=27.5dBm
		-42		dBc	MPM, P_{OUT}=19.0dBm
		-42		dBc	LPM, P_{OUT}=8.0dBm
ACLR - 3.2MHz Offset	-56.0	-57.5		dBc	HPM, P_{OUT}=27.5dBm
		-60		dBc	MPM, P_{OUT}=19.0dBm
		-63		dBc	LPM, P_{OUT}=8.0dBm
PAE Without DC/DC Converter		35		%	HPM, P_{OUT}=27.5dBm
		20		%	MPM, P_{OUT}=19.0dBm
		4.5		%	LPM, P_{OUT}=8.0dBm
Current Drain		425		mA	HBM, P_{OUT}=27.5dBm (during active timeslot)
		120		mA	LPM, P_{OUT}=19dBm (during active timeslot)
		40		mA	LPM, P_{OUT}=8.0dBm (during active timeslot)
Quiescent Current		85		mA	HPM, DC only
		20		mA	MPM, DC only
		17		mA	LPM, DC only
Enable Current		0.3	1.0	mA	Source or sink current. V_{EN}=1.8V.
Mode Current (I_{MODE0}, I_{MODE1})		0.3	1.0	mA	Source or sink current. V_{MODE0}, V_{MODE1}=1.8V.
Leakage Current		1.0	10.0	µA	DC only. V_{EN}=V_{MODE0}=V_{MODE1}=0.5V.
Input Impedance		2.0:1		VSWR	No ext. matching, P_{OUT}≤27dBm, all modes.
Harmonic, 2FO		-28		dBm	P_{OUT}≤27.5dBm, HPM.
Harmonic, 3FO		-35		dBm	P_{OUT}≤27.5dBm, HPM.
SEM Margin		3		dB	P_{OUT}=27.5dBm, HPM
Spurious Output Level			-70	dBc	All spurious, P_{OUT}≤27.5dBm, all conditions, load VSWR≤6:1, all phase angles.
Insertion Phase Shift	-30		+30	°	Phase shift at 19dBm when switching from HPM to MPM and MPM to LPM at 8dBm.
DC Enable Time			10	µS	DC only. Time from V_{EN}=high to stable idle current (90% of steady state value).
RF Rise/Fall Time			6	µS	P_{OUT}≤27.5dBm, all modes. 90% of target, DC settled prior to RF.
Coupling Factor		-19.5		dB	P_{OUT}≤27.5dBm, all modes.
Coupling Accuracy - Temp/Voltage		±0.5		dB	P_{OUT}≤27.5dBm, all modes. -25°C≤T≤85°C. See W-CDMA condition notes.
Coupling Accuracy - VSWR		±0.5		dB	P_{OUT}≤27.5dBm, all modes, load VSWR=2:1.
EVM		1.8		%	P_{OUT}=27.5dBm, V_{CC}=3.4V

Note: [1]Excludes DC/DC converter operation. Gain may be lower when using DC/DC converter to conserve battery current.
Note: [2]Unless otherwise marked , each spec is equivalent for W-CDMA or TD-SCDMA operation.

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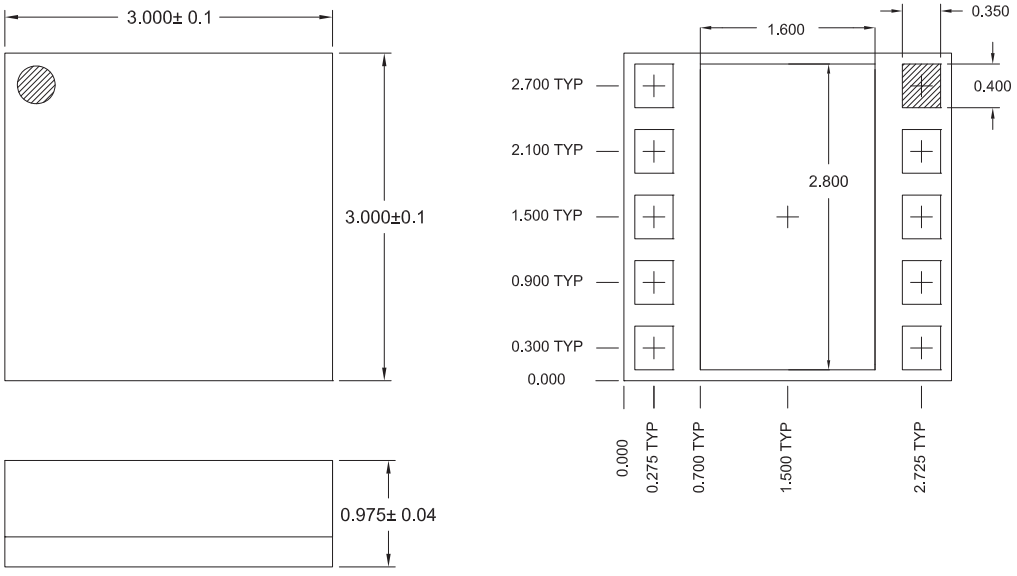
Pin	Function	Description
1	VBAT	Supply voltage for bias circuitry and the first stage amplifier.
2	RF IN	RF input internally matched to 50Ω and DC blocked.
3	VMODE1	Digital control input for power mode selection (see Operating Modes truth table).
4	VMODE0	Digital control input for power mode selection (see Operating Modes truth table).
5	VEN	Digital control input for PA enable and disable (see Operating Modes truth table).
6	CPL_OUT	Coupler output.
7	GND	This pin must be grounded.
8	CPL_IN	Coupler input used for cascading couplers in series. Terminate this pin with a 50Ω resistor if not connected to another coupler.
9	RF OUT	RF output internally matched to 50Ω and DC blocked.
10	VCC	Supply voltage for the second stage amplifier which can be connected to battery supply or output of DC-DC converter.
Pkg Base	GND	Ground connection. The package backside should be soldered to a topside ground pad connecting to the PCB ground plane with multiple ground vias. The pad should have a low thermal resistance and low electrical impedance to the ground plane.

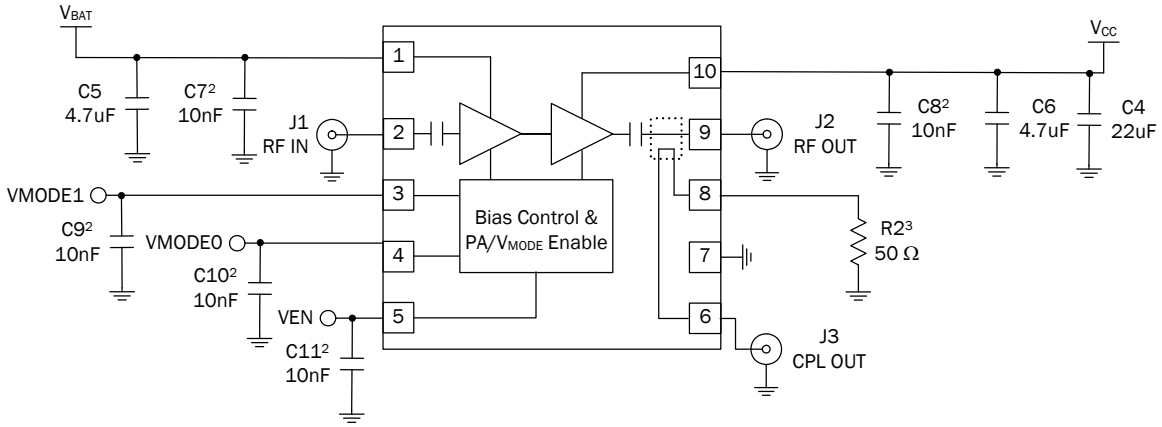
V_{EN}	V_{MODE0}	V_{MODE1}	V_{BAT}	V_{CC}	Conditions/Comments
Low	Low	Low	3.4V to 3.8V	3.4V to 3.8V	Power down mode
Low	X	X	3.4V to 3.8V	3.4V to 3.8V	Standby Mode
High	Low	Low	3.4V to 3.8V	3.4V to 3.8V	High power mode
High	High	Low	3.4V to 3.8V	3.4V to 3.8V	Medium power mode
High	High	High	3.4V to 3.8V	3.4V to 3.8V	Low power mode
High	High	High	3.4V to 3.8V	≥0.5V	Optional lower V_{CC} in low power mode

Package Drawing



NOTES:
1. SHADED AREAS REPRESENT PIN 1 LOCATION.

Preliminary Application Schematic

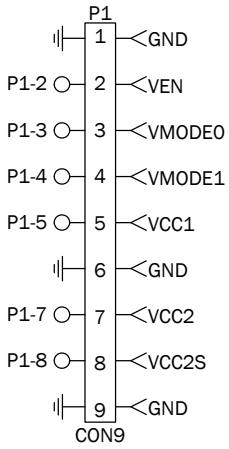


NOTES:

1 VCC and VBAT are connected together if DC-DC converter is not used.

2 Place these capacitors as close to PA as possible.

3 50 Ω resistor will be removed if pin 8 is connected to another coupler.



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PCB Design Requirements

PCB Surface Finish

The PCB surface finish used for RFMD's qualification process is electroless nickel, immersion gold. Typical thickness is 3μinch to 8μinch gold over 180μinch nickel.

PCB Land Pattern Recommendation

PCB land patterns for RFMD components are based on IPC-7351 standards and RFMD empirical data. The pad pattern shown has been developed and tested for optimized assembly at RFMD. The PCB land pattern has been developed to accommodate lead and package tolerances. Since surface mount processes vary from company to company, careful process development is recommended.

PCB Metal Land Pattern

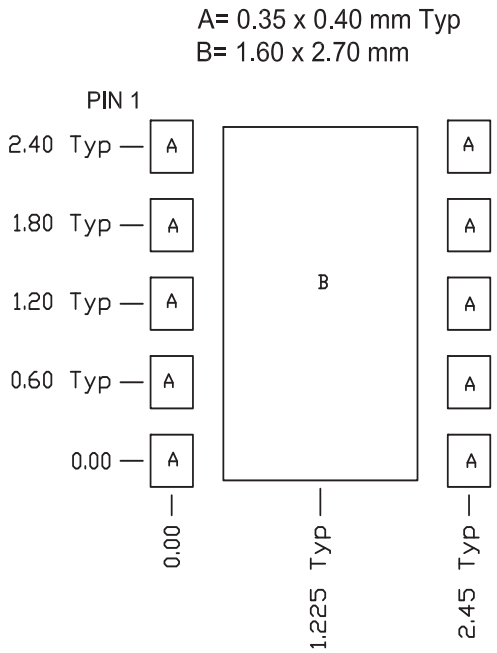

Figure 1. PCB Metal Land Pattern (Top View)

PCB Solder Mask Pattern

Liquid Photo-Imageable (LPI) solder mask is recommended. The solder mask footprint will match what is shown for the PCB metal land pattern with a 2mil to 3mil expansion to accommodate solder mask registration clearance around all pads. The center-grounding pad shall also have a solder mask clearance. Expansion of the pads to create solder mask clearance can be provided in the master data or requested from the PCB fabrication supplier.

A= 0.45 x 0.50 mm Typ
B= 1.70 x 2.80 mm

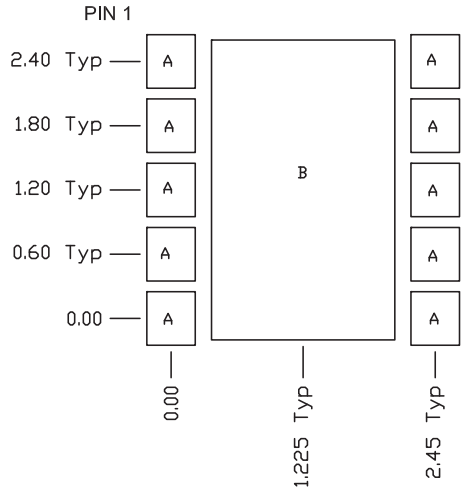

Figure 2. PCB Solder Mask Pattern (Top View)

Thermal Pad and Via Design

The PCB land pattern has been designed with a thermal pad that matches the die paddle size on the bottom of the device.

Thermal vias are required in the PCB layout to effectively conduct heat away from the package. The via pattern has been designed to address thermal, power dissipation and electrical requirements of the device as well as accommodating routing strategies.

The via pattern used for the RFMD qualification is based on thru-hole vias with 0.203mm to 0.330mm finished hole size on a 0.5mm to 1.2mm grid pattern with 0.025mm plating on via walls. If micro vias are used in a design, it is suggested that the quantity of vias be increased by a 4:1 ratio to achieve similar results.

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